

# Single-Event Characterization of the 16 nm FinFET Xilinx Kintex UltraScale+ Field-Programmable Gate Array in Heavy Ion Irradiation

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## Abstract

This study examines the single-event response of the Xilinx 16 nm FinFET-based Kintex UltraScale Field-Programmable Gate Array (FPGA) irradiated with heavy ions. Results for single-event upset on configuration SRAM cells are provided, which show excellent SEU performance compared to previous Xilinx FPGA families. This study also describes a destructive single-event latch-up signature observed during testing.

## Introduction

This study examines the single-event effects susceptibility of the latest UltraScale+ FPGA device family from Xilinx. These FPGAs are built with a TSMC 16 nm FinFET process and are categorized into Kintex, Virtex, and Zynq MPSoC families. The DUT selected for this experiment has the following characteristics:

Device	Xilinx Kintex UltraScale+ XCKU9P (ES2)
Package	FFVE900E (flip-chip, extended temperature grade)
Configuration	212,086,240 bits
Flip-Flops	548,160
BlockRAM™	32.1 Mbits (912 @ 36kb each)
Look-up Tables	274,080 LUTs, 6-input
Other device features	4 clock management tiles (total 4 MMCMs and 8 PLLs), 28 Transceiver blocks (16.3 Gbps), 10-bit ADC, 2,520 DSP slices



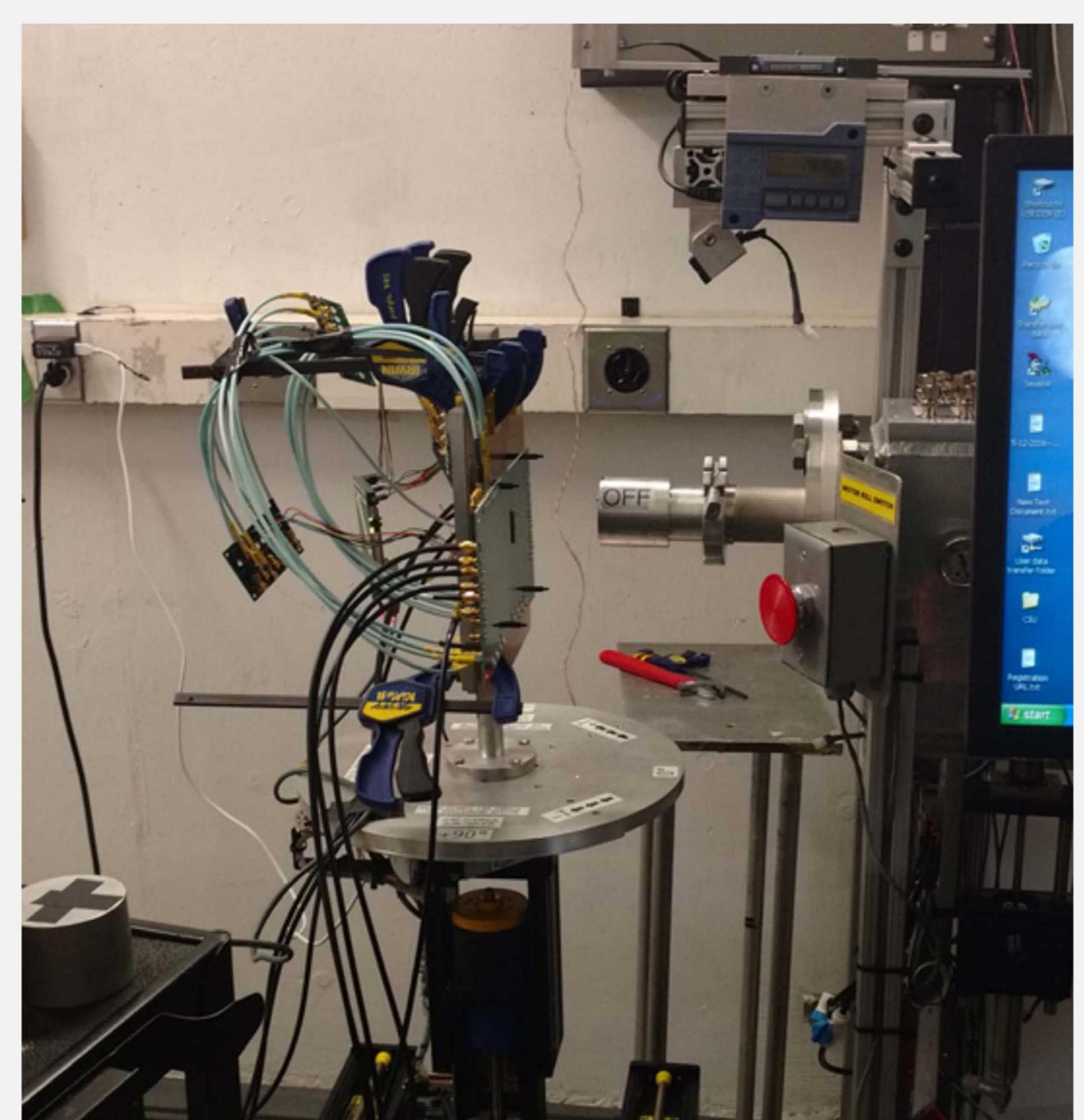
## Test and Beam Parameters

This device was tested at the Texas A&M K500 Cyclotron in May of 2017. Irradiation was performed using Argon and Neon, which provided LETs ranging from 3.2 to 20.1 MeV-cm<sup>2</sup>/mg.

All irradiations were performed at normal incidence and at room temperature.

Prior to each run, the device was power cycled and programmed static design, comprised of pre-initialized flip-flop shift registers and BlockRAM. There was no running clock during the irradiation.

Scrubbing and readback operations were performed with the BYU JTAG Configuration Monitor using the FPGA's JTAG interface.



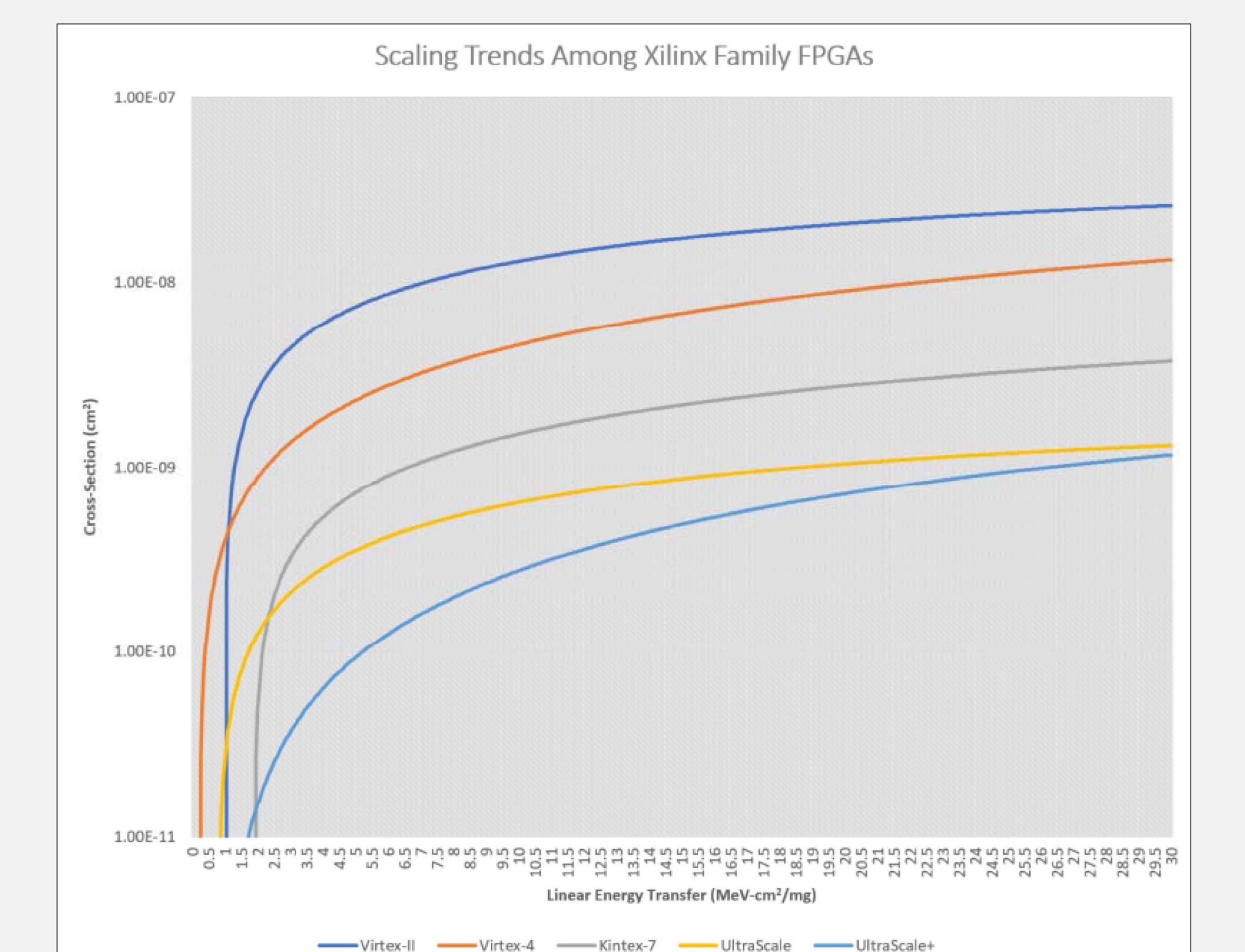
## Comparison to Previous Families

The SEU susceptibility of the Kintex UltraScale+ was compared to previous Xilinx families. There is significant improvement in SEU response, likely due to device scaling and the new FinFET-based transistor structures.

Configuration Memory Rates			
	per bit, per day	Improvement*	Node
Virtex-II	3.99E-07	1	130 nm
Virtex-4	2.63E-07	1.517	90 nm
Kintex-7	1.41E-08	28.298	28 nm
UltraScale	7.56E-09	52.778	20 nm
UltraScale+	1.33E-09	300.000	16 nm

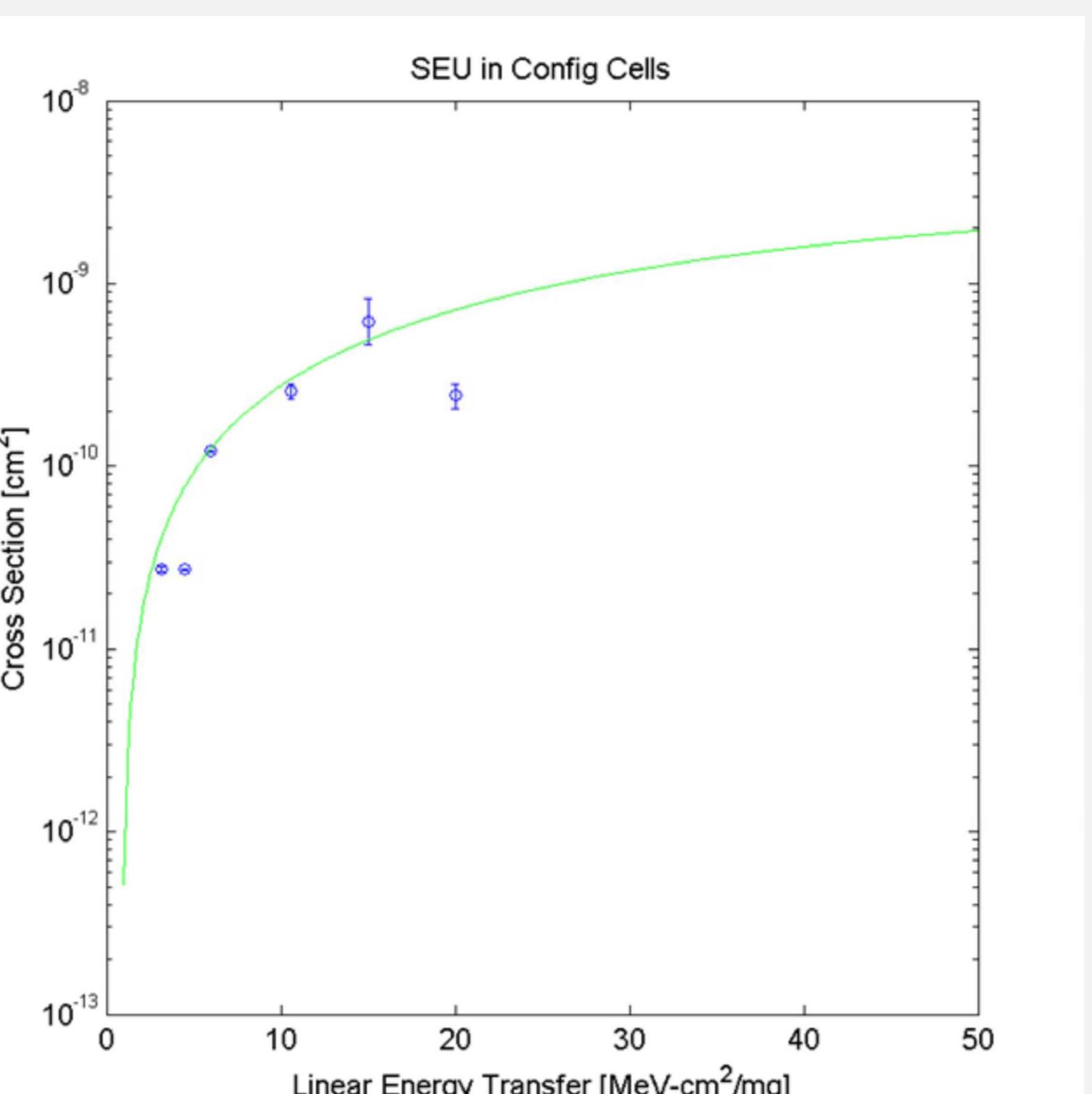
\* compared to Virtex-II

Virtex-II and Virtex-4 data was gathered from:  
[Virtex-II] R. King, J. George, G. Swift, S. Yu, L. Edwards, C. Cornish, T. Langley, P. Murray, K. Lanes, and M. S. Taylor, "Comparison of SEU rates for the Virtex-II and Virtex-4 families using proton and heavy ion test methods," in Proc. IEEE Nuclear Science Symposium and Medical Imaging Conference, vol. 3, pp. 2825-2833, 2004.  
[Virtex-4] G. Alton, G. Swift, C. Cornish, C. Teng, and C. Miller, "Upset measurements on Mid-Atom Virtex-4 FPGAs incorporating 90 nm features and the process layer," in Proc. IEEE Nuclear Science Symposium and Medical Imaging Conference, vol. 3, pp. 2825-2833, 2004.



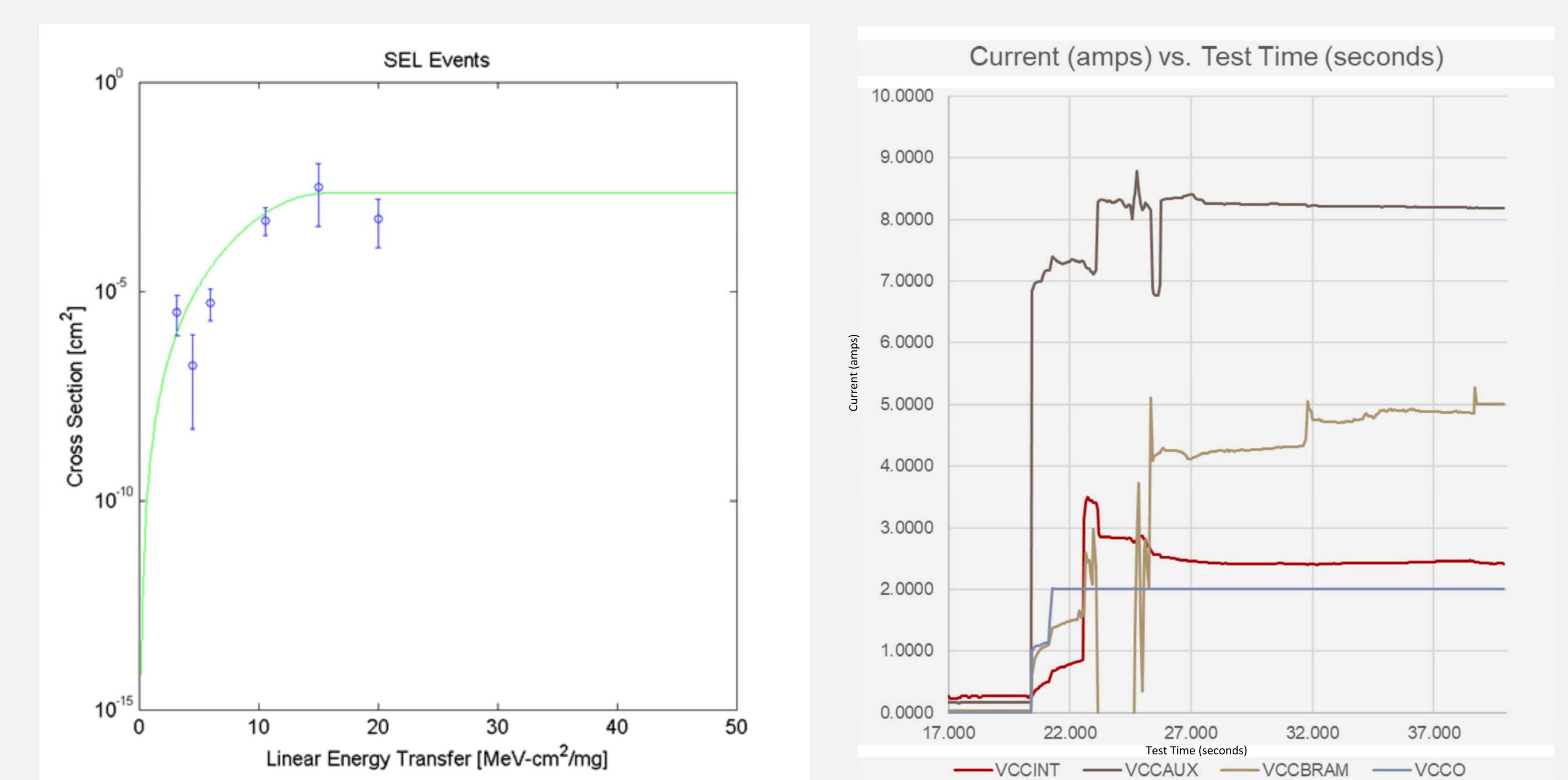
## Single-Event Upset Results

- Static configuration memory test was performed by configuring, irradiating, and then reading back the device.
- Comparisons were masked to only include bits pertinent to device operation and to exclude dynamic content (such as user flip-flop data). The mask file provided by the Xilinx Vivado tools was used for this purpose. This led to an approximate total of 119 million bits being observed for upset.
- After normalizing the results for the number of 0s and 1s in the bitstream, the configuration cells storing "0" values appeared to upset more often than bits storing "1" by a ratio of ~4:1



## Single-Event Latch-up Results

- Single-Event Latch-up was observed at LET of 3.2 MeV-cm<sup>2</sup>/mg at ambient temperature and normal voltage biases. (The actual LET threshold may be lower; testing was not performed below this LET)
- The VCCAUX power rail was always the first observed rail where a SEL event would begin.
- Latch-up-like behavior on other rails was observed, but always happened following a SEL on VCCAUX (probably due to die temperature increase).
- The device was non-functional following a SEL event where the current was not limited by the power supply and multiple latch-up sites were allowed to collect in the device. A graph of the current draw per power rail is shown below.



## Event Rates

The event rates from CREME96 are listed below, assuming a GEO orbit, solar minimum conditions, and 100 mils of aluminum shielding:

	Configuration Memory	SEL Events
Per Bit	1.33E-9 / day	N/A
Per Device	0.28 / day (on 212M bits)	~0.01 / day